

74LVC1G126

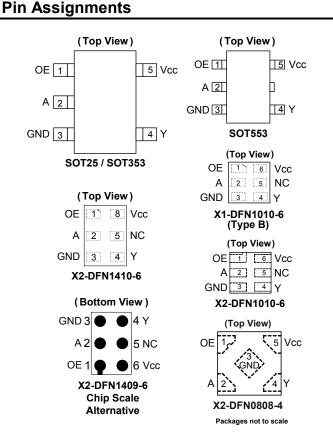
# SINGLE BUFFER GATE WITH 3-STATE OUTPUT

#### Description

The 74LVC1G126 is a single, non-inverting buffer/bus driver with a 3-state output. The output enters a high-impedance state when a LOW level is applied to the output enable (OE) pin. The device is designed for operation with a power supply range of 1.65V to 5.5V. The inputs are tolerant to 5.5V allowing this device to be used in a mixed-voltage environment. The device is fully specified for partial power down applications using I<sub>OFF</sub>. The I<sub>OFF</sub> circuitry disables the output preventing damaging current backflow when the device is powered down.

#### Features

- Wide Supply Voltage Range from 1.65V to 5.5V
- ±24mA Output Drive at 3.3V
- **CMOS Low Power Consumption**
- IOFF Supports Partial-Power-Down Mode Operation
- Inputs Accept Up to 5.5V
- ESD Protection Tested per JESD 22
  - Exceeds 200V Machine Model (A115)
  - Exceeds 2000V Human Body Model (A114)
  - Exceeds 1000V Charged Device Model (C101)
- Latch-Up Exceeds 100mA per JESD 78, Class I
- Range of Package Options
- Direct Interface with TTL Levels
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)



#### Applications

- Voltage Level Shifting
- General Purpose Logic
- Power Down Signal Isolation
- Wide Array of Products Such as.
  - PCs, Networking, Notebooks, Netbooks, PDAs
  - Tablet Computers, E-Readers
  - Computer Peripherals, Hard Drives, CD/DVD ROM
  - TV, DVD, DVR, Set-Top Box
  - Cell Phones. Personal Navigation/GPS
  - MP3 Players, Cameras, Video Recorders

Notes:

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.

- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.



# Ordering Information (Note 4)

		<u>74 LVC1G</u> 126 X	<u> </u>	
Logic Device		Function	Package	Packing
74 : Logic Prefix LVC : 1.65 to 5.5 V Logic Family 1G : One Gate	126:	3-State Buffer OE active HIGH	W5 : SOT25 SE : SOT353 Z : SOT553 FS3 : X2-DFN0808-4 FW5 : X1-DFN1010-6 FW4 :X2-DFN1010-6 FX4 : X2- DFN1409-6 FZ4 : X2- DFN1410-6	-7 : 7" Tape & Reel (Туре В)

Part Number	Package	Package	Package	7" Tape a	and Reel
Part Number	Code	(Notes 5 & 6)	Size	Quantity	Part Number Suffix
74LVC1G126W5-7	W5	SOT25	3.0mm × 2.8mm × 1.2mm 0.95mm lead pitch	3000/Tape & Reel	-7
74LVC1G126SE-7	SE	SOT353	2.0mm × 2.0mm × 1.1mm 0.65mm lead pitch	3000/Tape & Reel	-7
74LVC1G126Z-7	UVC1G1267-7 7 SOT553		1.6mm × 1.6 mm × 0.62mm 0.5mm lead pitch	4000/Tape & Reel	-7
74LVC1G126FS3-7	FS3	X2-DFN0808-4	0.8mm × 0.8mm × 0.35mm 0.5mm pad pitch (diamond)	5000/Tape & Reel	-7
74LVC1G126FW5-7	FW5	X1-DFN1010-6 (Type B)	1.0mm × 1.0mm × 0.5mm 0.35mm pad pitch	5000/Tape & Reel	-7
74LVC1G126FW4-7	FW4	X2-DFN1010-6	1.0mm × 1.0mm × 0.4mm 0.35mm pad pitch	5000/Tape & Reel	-7
74LVC1G126FX4-7	FX4	X2-DFN1409-6 (Chip scale alternative)	1.4mm × 0.9mm × 0.4mm 0.5mm pad pitch	5000/Tape & Reel	-7
74LVC1G126FZ4-7	FZ4	X2-DFN1410-6	1.4mm × 1.0mm × 0.4mm 0.5mm pad pitch	5000/Tape & Reel	-7

4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

5. Pad layout as shown on Diodes Inc. suggested pad layout which can be found on our website at http://www.diodes.com/package-outlines.html.

6. The taping orientation is located on our website at http://www.diodes.com/datasheets/ap02007.pdf.

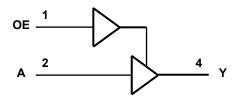
# Pin Name Description OE Output Enable A Data Input GND Ground Y Data Output Vcc Supply Voltage NC No Connection

# **Function Table**

Notes:

Inj	outs	Output
OE	Α	Y
Н	Н	Н
Н	L	L
L	Х	Z

# Logic Diagram





Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	kV
ESD CDM	Charged Device Model ESD Protection	1	kV
ESD MM	Machine Model ESD Protection	200	V
Vcc	Supply Voltage Range	-0.5 to +6.5	V
VI	Input Voltage Range	-0.5 to +6.5	V
Vo	Voltage Applied to Output in High Impedance or IOFF State	-0.5 to +6.5	V
Vo	Voltage Applied to Output in High or Low State	-0.5 to V <sub>CC</sub> +0.5	V
I <sub>IK</sub>	Input Clamp Current VI < 0	-50	mA
I <sub>OK</sub>	Output Clamp Current	-50	mA
lo	Continuous Output Current	±50	mA
I <sub>CC</sub> , I <sub>GND</sub> Continuous Current Through V <sub>CC</sub> or GND		±100	mA
TJ	Operating Junction Temperature	-40 to +150	°C
T <sub>STG</sub>	Storage Temperature	-65 to +150	°C

#### Absolute Maximum Ratings (Notes 7 & 8) (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Notes: 7. Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.

8. Forcing the maximum allowed voltage could cause a condition exceeding the maximum current or conversely forcing the maximum current could cause a condition exceeding the maximum voltage. The ratings of both current and voltage must be maintained within the controlled range.

#### Recommended Operating Conditions (Note 9) (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Symbol		Parameter	Min	Max	Unit	
		Operating	1.65	5.5	V	
Vcc	Operating Voltage	Data retention only	1.5	15	V	
		V <sub>CC</sub> = 1.65V to 1.95V	0.65 x V <sub>CC</sub>	—		
		V <sub>CC</sub> = 2.3V to 2.7V	1.7	—		
V <sub>IH</sub>	High-Level Input Voltage	V <sub>CC</sub> = 3V to 3.6V	2	—	V	
		V <sub>CC</sub> = 4.5V to 5.5V	0.7 x V <sub>CC</sub>	—		
		V <sub>CC</sub> = 1.65V to 1.95V	_	0.35 × V <sub>CC</sub>		
		V <sub>CC</sub> = 2.3V to 2.7V	_	0.7	.,	
VIL	Low-Level Input Voltage	V <sub>CC</sub> = 3V to 3.6V	_	0.8	V	
		V <sub>CC</sub> = 4.5V to 5.5V	_	0.3 × V <sub>CC</sub>		
VI	Input Voltage	•	0	5.5	V	
Vo	Output Voltage		0	V <sub>CC</sub>	V	
		V <sub>CC</sub> = 1.65V	_	-4		
		V <sub>CC</sub> = 2.3V	_	-8		
	High-Level Output Current	V <sub>CC</sub> = 2.7V	_	-12	mA	
I <sub>OH</sub>		V <sub>cc</sub> = 3V	—	-16	IIIA	
			_	-24		
		$V_{CC} = 4.5V$	—	-32		
		V <sub>CC</sub> = 1.65V	—	4		
		$V_{CC} = 2.3V$	—	8		
	Low Lovel Output Current	V <sub>CC</sub> = 2.7V	_	12		
I <sub>OL</sub>	Low-Level Output Current	V <sub>cc</sub> = 3V	_	16	mA	
		V <sub>CC</sub> – 3V	—	24		
		$V_{CC} = 4.5V$	—	32		
		V <sub>CC</sub> = 1.8V ± 0.15V, 2.5V ± 0.2V	—	20		
Δt/ΔV	Input transition Rise or Fall Rate	$V_{CC} = 3.3V \pm 0.3V$	—	10	ns/V	
		$V_{CC} = 5V \pm 0.5V$	_	5	1	
TA	Operating Free-Air Temperature	_	-40	+125	°C	

Note: 9. Unused inputs should be held at  $V_{CC}$  or Ground.



#### Electrical Characteristics (All typical values are at $V_{CC}$ = 3.3V, $T_A$ = +25°C)

0	Demonstern	Tast Osmalitisms	M	-4	40°C to +85°	С	-40°C to	+125°C	11
Symbol	Parameter	Test Conditions	Vcc	Min	Тур	Max	Min	Мах	Unit
		I <sub>OH</sub> = -100μA	1.65V to 5.5V	V <sub>CC</sub> -0.1	—	—	V <sub>CC</sub> -0.1	—	
		I <sub>OH</sub> = -4mA	1.65V	1.2	—	—	0.95	—	
		I <sub>OH</sub> = -8mA	2.3V	1.9	—	_	1.7		
Voh	High Level Output Voltage	I <sub>OH</sub> = -12mA	2.7V	2.2	—	_	1.9		V
	Vonago	I <sub>OH</sub> = -16mA	3V	2.4	—	_	2.2		
		I <sub>OH</sub> = -24mA	37	2.3	_	_	2.0		
		I <sub>OH</sub> = -32mA	4.5V	3.8	_	_	3.4		
		I <sub>OL</sub> = 100μA	1.65V to 5.5V	—	_	0.1	—	0.1	
		I <sub>OL</sub> = 4mA	1.65V	—	_	0.45	—	0.7	
		I <sub>OL</sub> = 8mA	2.3V	—	—	0.3	—	0.45	
V <sub>OL</sub>	Low Level Output Voltage	I <sub>OL</sub> = 12mA	2.7V	—	—	0.4	—	0.6	V
	Vonago	I <sub>OL</sub> = 16mA	3V	—	—	0.4	—	0.6	
		I <sub>OL</sub> = 24mA	30	—	—	0.55	—	0.8	
		I <sub>OL</sub> = 32mA	4.5V	—	—	0.55	—	8	
lı –	Input Current	V <sub>I</sub> = 5.5V or GND	0 to 5.5V	—	± 0.1	±5	—	±100	μA
IOFF	Power Down Leakage Current	$V_1$ or $V_0$ = 5.5V	0V	—	_	±10	—	±200	μA
I <sub>OZ</sub>	Z State Leakage Current	V <sub>O</sub> =0 to 5.5V	3.6V	_	0.1	10	—	20	μA
Icc	Supply Current	$V_1 = 5.5V \text{ or GND}$ $I_0 = 0$	5.5V	_	0.1	10	_	200	μA
ΔI <sub>CC</sub>	Additional Supply Current	One input at $V_{CC}$ -0.6 V Other inputs at $V_{CC}$ or GND	3V to 5.5V	_	_	500	_	5000	μA
Ci	Input Capacitance	$V_{I} = V_{CC} - or GND$	3.3V	_	5	_	_	_	pF

# Package Characteristics (All typical values are at $V_{CC}$ = 3.3V, $T_A$ = +25°C)

Symbol	Parameter	Test Conditions	Vcc	Min	Тур	Мах	Unit
		SOT25		—	204	—	
		SOT353	-	_	371	—	
		SOT553	-	_	231	—	
0	Thermal Resistance	X2-DFN0808-4	(Nata 10)	_	400	—	°0111
$\theta_{JA}$	Junction-to-Ambient	X1-DFN1010-6 (Type B)	(Note 10)	_	435	—	°C/W
		X2-DFN1010-6		_	445	—	
		X2-DFN1409-6	-	_	470	—	
		X2-DFN1410-6	-	_	460	—	
		SOT25		—	52	—	
		SOT353	-	_	143	—	
		SOT553	-	_	105	—	
0	Thermal Resistance	X2-DFN0808-4	(Neta 10)	_	225	—	°C M
$\theta_{JC}$	Junction-to-Case	X1-DFN1010-6 (Type B)	(Note 10)	_	250	—	°C/W
		X2-DFN1010-6	-	_	250	—	
		X2-DFN1409-6	]	_	275	—	
		X2-DFN1410-6	]	_	265	_	

Note: 10. Test condition for each of the eight package types: Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.



# **Switching Characteristics**

Parameter	From	То	Maa	ΤΑ =	= -40°C to +8	35°C	T <sub>A</sub> = -40°C	to +125°C	Unit
Input	Output	Vcc	Min	Тур	Max	Min	Max	0111	
			1.8V ± 0.15V	1.0	3.0	8.0	1.0	10.5	
			2.5V ± 0.2V	0.5	2.1	5.5	0.5	7.0	
t <sub>pd</sub>	А	Y	2.7V	0.5	2.3	5.5	0.5	7.5	ns
			3.3V ± 0.3V	0.5	2.0	4.5	0.5	6.0	
			5.0V ± 0.5V	0.5	1.7	4.0	0.5	5.5	
			1.8V ± 0.15V	1.0	3.2	9.4	1.0	12.0	
			2.5V ± 0.2V	0.5	2.2	6.6	0.5	8.5	
t <sub>en</sub>	OE	Y	2.7V	0.5	2.4	6.6	0.5	8.5	ns
			3.3V ± 0.3V	0.5	2.1	5.3	0.5	7.0	
			5.0V ± 0.5V	0.5	1.6	5.0	0.5	6.5	
			1.8V ± 0.15V	1.0	4.3	9.2	1.0	12.0	
			2.5V ± 0.2V	0.5	2.7	5.5	0.5	7.0	
t <sub>dis</sub>	OE	Y	2.7V	0.5	3.4	5.5	0.5	7.0	ns
			3.3V ± 0.3V	0.5	3.0	5.5	0.5	7.0	
			5.0V ± 0.5V	0.5	2.2	4.2	0.5	5.5	

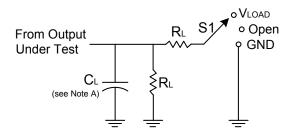
# **Operating Characteristics**

T<sub>A</sub> = +25°C

	Parameter		Test Conditions	V <sub>CC</sub> = 1.8V Typ	V <sub>CC</sub> = 2.5V Typ	V <sub>CC</sub> = 3.3V Typ	V <sub>CC</sub> = 5V Typ	Unit
0	Power Dissipation	Outputs Enabled	£ - 40MU-	19	19	19	21	~ <b>F</b>
C <sub>pd</sub>	Capacitance	Outputs Disabled	f = 10MHz	2	2	3	4	рF

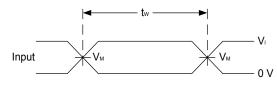


#### **Parameter Measurement Information**

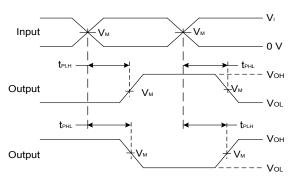


TEST	S1
t <sub>PLH</sub> /t <sub>PHL</sub>	Open
t <sub>PLZ</sub> /t <sub>PZL</sub>	V <sub>LOAD</sub>
t <sub>PHZ</sub> /t <sub>PZH</sub>	GND

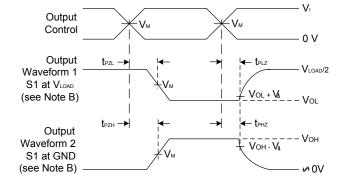
N	Inp	outs	V	N	6		MA
V <sub>cc</sub>	VI	t <sub>r</sub> /t <sub>f</sub>	V <sub>M</sub>	V <sub>LOAD</sub>	C∟	RL	VΔ
1.8V±0.15V	Vcc	≤2ns	V <sub>CC</sub> /2	2 x V <sub>CC</sub>	30pF	1kΩ	0.15V
2.5V±0.2V	Vcc	≤2ns	V <sub>CC</sub> /2	2 x V <sub>CC</sub>	30pF	500Ω	0.15V
2.7V	2.7V	≤2.5ns	1.5V	6V	50pF	500Ω	0.3V
3.3V±0.3V	3V	≤2.5ns	1.5V	6V	50pF	500Ω	0.3V
5V±0.5V	Vcc	≤2.5ns	V <sub>CC</sub> /2	$2 \times V_{CC}$	50pF	500Ω	0.3V



**Voltage Waveform Pulse Duration** 







#### Voltage Waveform Enable and Disable Times Low and High Level Enabling

#### Figure 1 Load Circuit and Voltage Waveforms

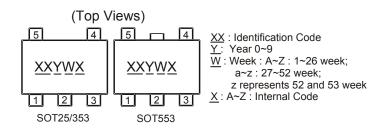
Notes: A. Includes test lead and test apparatus capacitance.

- B. All pulses are supplied at pulse repetition rate ≤ 10MHz.
   C. Inputs are measured separately one transition per measurement.
- D. tPLZ and tPHZ are the same as tdis.
- E. t<sub>PZL</sub> and t<sub>PZH</sub> are the same as t<sub>EN</sub>.
- F. tPLH and tPHL are the same as tPD.



#### **Marking Information**

#### (1) SOT25, SOT353 and SOT553



Part Number	Package	Identification Code
74LVC1G126W5-7	SOT25	UZ
74LVC1G126SE-7	SOT353	UZ
74LVC1G126Z-7	SOT553	UZ

#### (2) DFN Packages

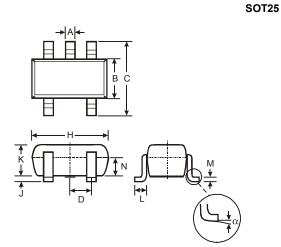


 $\begin{array}{l} \underline{XX}: \mbox{ Identification Code} \\ \underline{Y}: \mbox{ Year 0~9} \\ \underline{W}: \mbox{ Week : } A~Z: 1~26 week; \\ a~z: 27~52 week; \\ z \mbox{ represents 52 and 53 week} \\ \underline{X}: \mbox{ A~Z}: \mbox{ Internal Code} \end{array}$ 

Part Number	Package	Identification Code
74LVC1G126FS3-7	X2-DFN0808-4	WZ
74LVC1G126FW5-7	X1-DFN1010-6 (Type B)	VZ
74LVC1G126FW4-7	X2-DFN1010-6	UZ
74LVC1G126FX4-7	X2-DFN1409-6	MY
74LVC1G126FZ4-7	X2-DFN1410-6	UZ



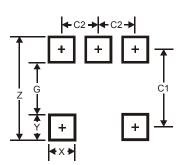
Please see http://www.diodes.com/package-outlines.html for the latest version.



	SOT25				
Dim	Min	Max	Тур		
Α	0.35	0.50	0.38		
В	1.50	1.70	1.60		
С	2.70	3.00	2.80		
D	-	-	0.95		
Н	2.90	3.10	3.00		
J	0.013	0.10	0.05		
κ	1.00	1.30	1.10		
L	0.35	0.55	0.40		
М	0.10	0.20	0.15		
Ν	0.70	0.80	0.75		
α	0°	8°	-		
All Dimensions in mm					

#### **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.



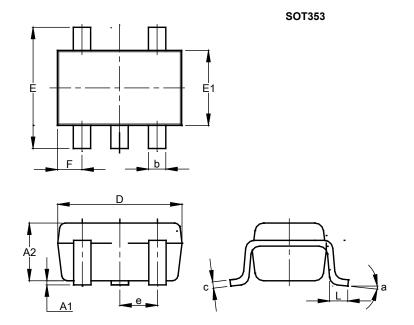
Dimensions	Value
Z	3.20
G	1.60
Х	0.55
Y	0.80
C1	2.40
C2	0.95

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SOT25



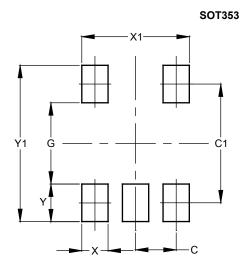
Please see http://www.diodes.com/package-outlines.html for the latest version.



	SOT353			
Dim	Min	Max	Тур	
A1	0.00	0.10	0.05	
A2	0.90	1.00	0.95	
b	0.10	0.30	0.25	
С	0.10	0.22	0.11	
D	1.80	2.20	2.15	
Е	2.00	2.20	2.10	
E1	1.15	1.35	1.30	
е	0.650 BSC			
F	0.40	0.45	0.425	
L	0.25	0.40	0.30	
а	0°	8°		
All Dimensions in mm				

# Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

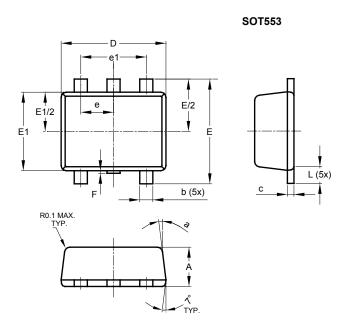


Dimensions	Value (in mm)
С	0.650
C1	1.900
G	1.300
Х	0.420
X1	1.720
Y	0.600
Y1	2.500

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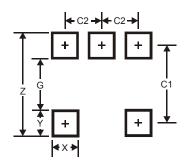
Please see http://www.diodes.com/package-outlines.html for the latest version.



	SOT	553	
Dim	Min	Max	Тур
Α	0.55	0.62	0.60
b	0.15	0.30	0.20
С	0.10	0.18	0.15
D	1.50	1.70	1.60
Е	1.55	1.70	1.60
E1	1.10	1.25	1.20
е	0.50 BSC		
e1	1.0	00 BS0	C
F	0.00	0.10	
L	0.10	0.30	0.20
а	6°	8°	7°
All Dimensions in mm			

# Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

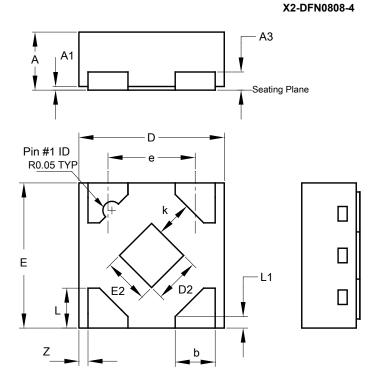


Dimensions		Value
Z	•	2.2
G	•	1.2
Х		0.375
Y		0.5
C1		1.7
C2		0.5

#### SOT553



Please see http://www.diodes.com/package-outlines.html for the latest version.

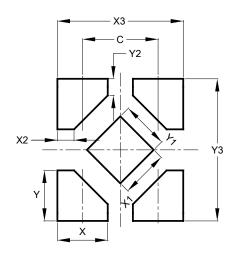


	X2-DFN0808-4				
Dim	Min	Max	Тур		
Α	0.25	0.35	0.30		
A1	0	0.04	0.02		
A3	-	-	0.13		
b	0.17	0.27	0.22		
D	0.75	0.85	0.80		
D2	0.15	0.35	0.25		
E	0.75	0.85	0.80		
E2	0.15	0.35	0.25		
е	-	-	0.48		
k	0.20	-	-		
L	0.17	0.27	0.22		
L1	0.02	0.12	0.07		
z	-	-	0.05		
All Dimensions in mm					

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

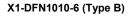
#### X2-DFN0808-4

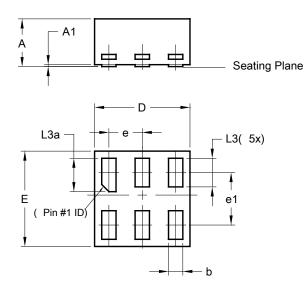


Dimensions	Value
С	0.480
Х	0.320
X1	0.300
X2	0.106
X3	0.800
Y	0.320
Y1	0.300
Y2	0.106
Y3	0.900



Please see http://www.diodes.com/package-outlines.html for the latest version.



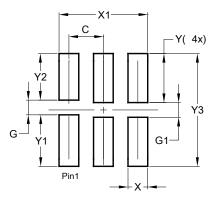


	X1-DFN1010-6 (Type B)				
Dim	Min	Max	Тур		
Α	-	0.50	0.39		
A1	-	0.04	-		
b	0.12	0.20	0.15		
D	0.95	1.050	1.00		
E	0.95	1.050	1.00		
е	0.35 BSC				
e1	0.55 BSC				
L3	0.27	0.30	0.30		
L3a	0.32	0.40	0.35		
All	All Dimensions in mm				

#### **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

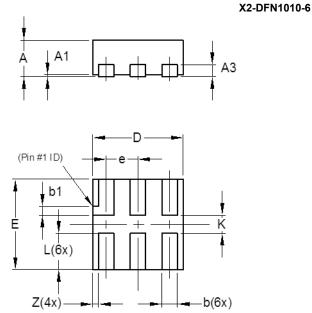
#### X1-DFN1010-6 (Type B)



Dimensions	Value (in mm)
С	0.350
G	0.150
G1	0.150
Х	0.200
X1	0.900
Y	0.500
Y1	0.525
Y2	0.475
Y3	1.150



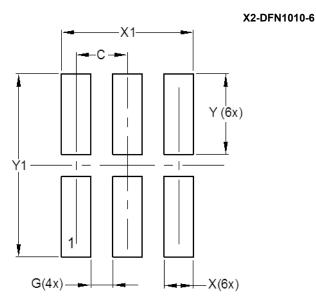
Please see http://www.diodes.com/package-outlines.html for the latest version.



X2-DFN1010-6				
Dim	Min	Max	Тур	
Α	_	0.40	0.39	
A1	0.00	0.05	0.02	
A3			0.13	
b	0.14	0.20	0.17	
b1	0.05	0.15	0.10	
D	0.95	1.05	1.00	
Е	0.95	1.05	1.00	
е	_	_	0.35	
L	0.35	0.45	0.40	
К	0.15	—	_	
Z	—	—	0.065	
All Dimensions in mm				

### **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

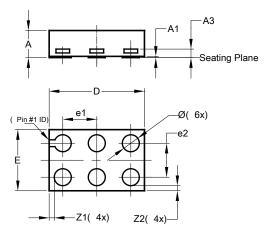


# Dimensions Value (in mm) C 0.350 G 0.150 X 0.200 X1 0.900 Y 0.550 Y1 1.250

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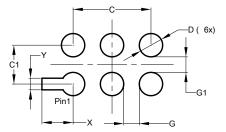
	X2-DFN1409-6			
Dim	Min	Max	Тур	
Α	-	0.40	0.39	
A1	0	0.05	0.02	
A3	-	-	0.13	
Ø	0.20	0.30	0.25	
D	1.35	1.45	1.40	
E	0.85	0.95	0.90	
e1	-	-	0.50	
e2	-	-	0.50	
Z1	-	-	0.075	
Z2	-	-	0.075	
All Dimensions in mm				

# Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### X2-DFN1409-6

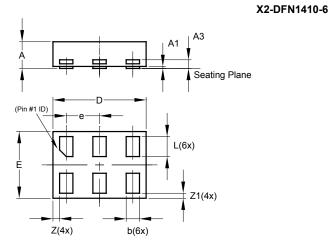
X2-DFN1409-6



Dimensions	Value (in mm)	
С	1.000	
C1	0.500	
D	0.300	
G	0.200	
G1	0.200	
Х	0.400	
Y	0.150	



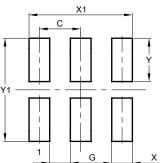
Please see http://www.diodes.com/package-outlines.html for the latest version.



X2-DFN1410-6				
Dim	Min	Max	Тур	
Α	_	0.40	0.39	
A1	0.00	0.05	0.02	
A3	_	_	0.13	
b	0.15	0.25	0.20	
D	1.35	1.45	1.40	
ш	0.95	1.05	1.00	
e	_	_	0.50	
L	0.25	0.35	0.30	
Z			0.10	
Z1	0.045	0.105	0.075	
All Dimensions in mm				

# Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



#### X2-DFN1410-6

Dimensions	Value (in mm)	
С	0.500	
G	0.250	
Х	0.250	
X1	1.250	
Y	0.525	
Y1	1.250	



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